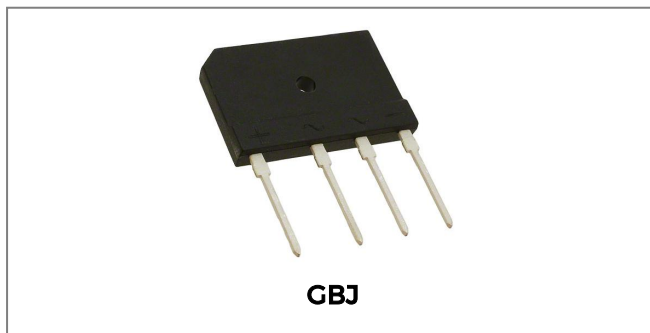


GBJ8005-GBJ810

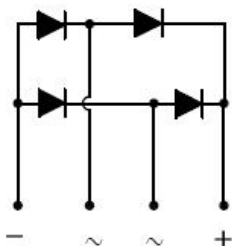
Single-Phase 8.0A Glass Passivated Bridge Rectifier



Features

- Glass passivated die construction
- Low forward voltage drop
- High current capability
- High surge current capability
- Plastic material-UL flammability 94V-0
- This is a Pb - Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Mechanical Data

- Case: GBJ, Molded plastic
- Terminals: Plated leads solderable per MIL-STD-202, Method 208
- Polarity: as marked on case
- Mounting Position: Any
- Lead Free: For RoHS / Lead Free Version
- Weight: 6.8 grams(approx)

Maximum Ratings @T_A=25°C unless otherwise specified

Type Number	Symbol	GBJ 8005	GBJ 801	GBJ 802	GBJ 804	GBJ 806	GBJ 808	GBJ 810	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_{DC}	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Average forward rectified output current (Note 1) @T _C =90°C	$I_{F(AV)}$	8.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	175							A
I ² t Rating for Fusing (t < 8.3ms)	I ² t	127.09							A ² s

Electrical Characteristics@T_A=25°C unless otherwise specified

Type Number	Symbol	GBJ 8005	GBJ 801	GBJ 802	GBJ 804	GBJ 806	GBJ 808	GBJ 810	Units
Forward Voltage (per element) @I _F =4A @I _F =8A	V _F	1.0 1.1							V
Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 125°C	I _{RM}	5.0 200							µA
Dielectric Strength	V _{ids}	2500							V
The proposed installation torque Max torque	T _{or}	Typ. 5.0 Max 8.0							Kgf.c m
Typical Junction Capacitance(per leg) (Note 2)	C _J	45							pF

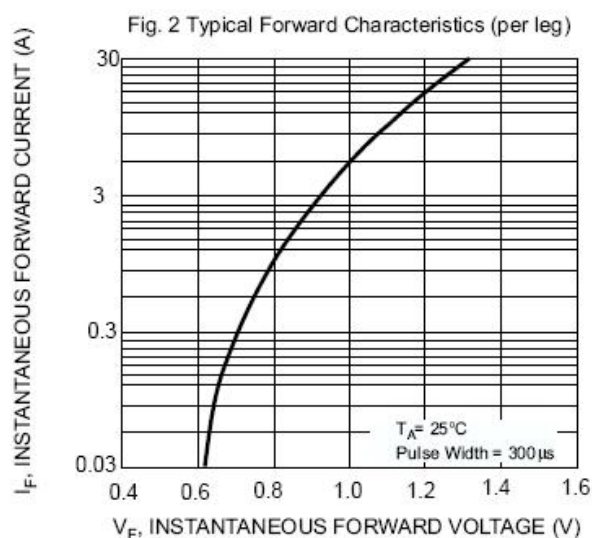
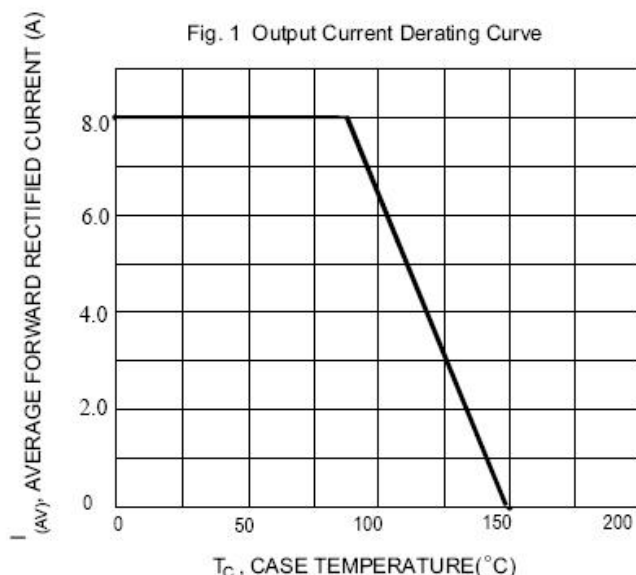
* Pulse width < 300 μs, duty cycle < 2%

Thermal-Mechanical Specifications:

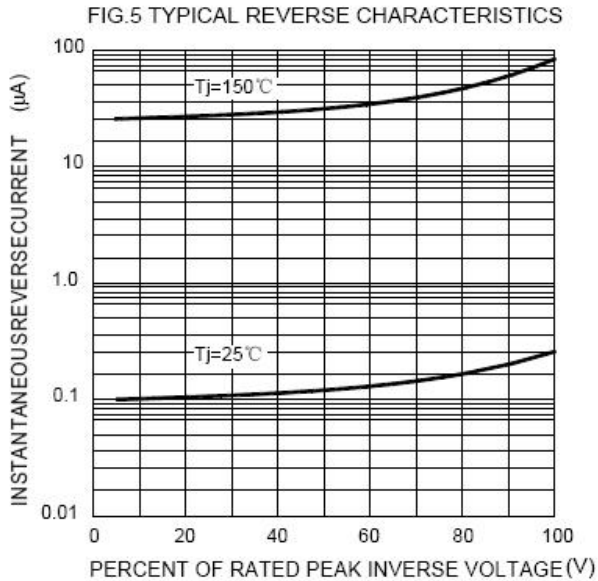
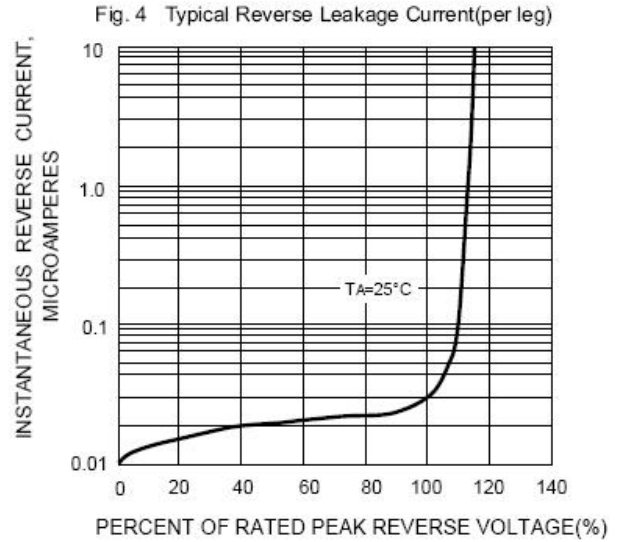
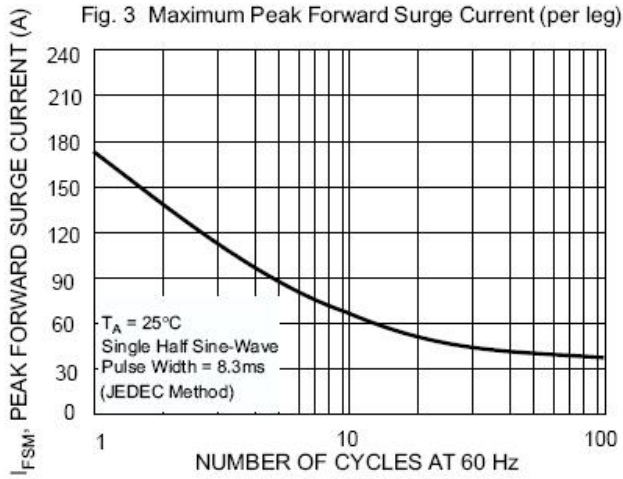
Type Number	Symbol	GBJ 8005	GBJ 801	GBJ 802	GBJ 804	GBJ 806	GBJ 808	GBJ 810	Units
Between junction and ambient, Without heatsink	R _{θJA}	24							°C/W
Between junction and case, With heatsink	R _{θJC}	2.0							°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150							°C

Note: 1. Unit case mounted on aluminum plate heatsink.
2. Measured at 1.0 MHz and applied reverse voltage of 5.0V D.C.

Ratings and Characteristics Curves



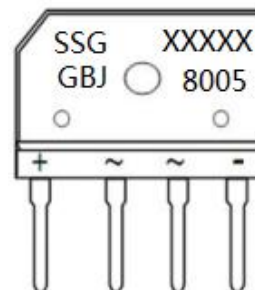
Technical Data
Data Sheet N2050, Rev. A



Ordering Information

Device	Package	Plating	Shipping
GBJ8005 THRU GBJ810	GBJ(Pb-Free)	Pure Sn	15pcs / tube

Marking Diagram

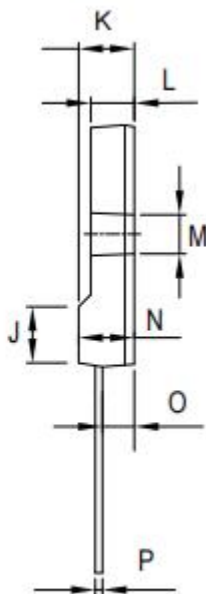
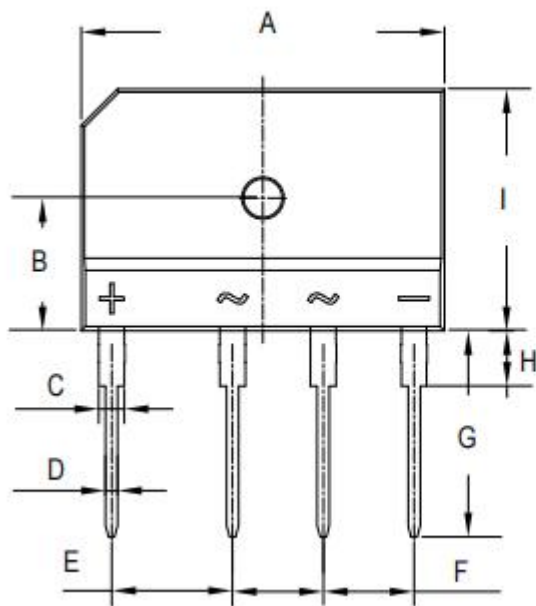


Where XXXXX is YYWWL

SSG = SSG
YY = Year
WW = Week
L = Lot Number
GBJ8005 = Type Number

Cautions: Molding resin
Epoxy resin UL94V-0

Mechanical Dimensions GBJ (Inches/Millimeters)



Dimensions	Millimeters		Inches	
	Min	Max	Min	Max
A	29.7	30.3	1.169	1.193
B	10.8	11.2	0.425	0.441
C	1.9	2.3	0.075	0.091
D	0.9	1.1	0.035	0.043
E	9.8	10.2	0.386	0.402
F	7.3	7.7	0.287	0.303
G	17.0	18.0	0.699	0.709
H	3.8	4.2	0.150	0.165
I	19.7	20.3	0.776	0.799
J	4.8	5.2	0.189	0.205
K	4.4	4.8	0.173	0.189
L	3.4	3.8	0.134	0.150
M	3.1	3.4	0.122	0.134
N	4.4	4.8	0.173	0.189
O	2.4	2.8	0.094	0.110
P	0.5	0.7	0.020	0.028

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